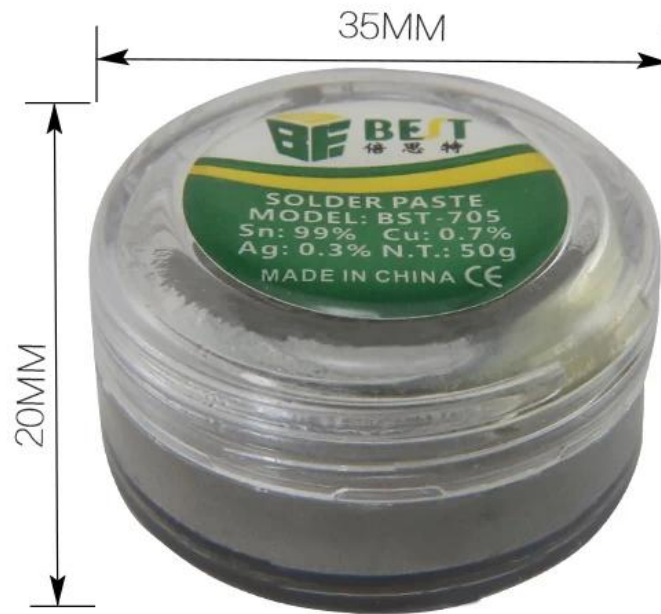


PRODUCT DISPLAY



PRODUCT DETAILS



Name: Solder paste

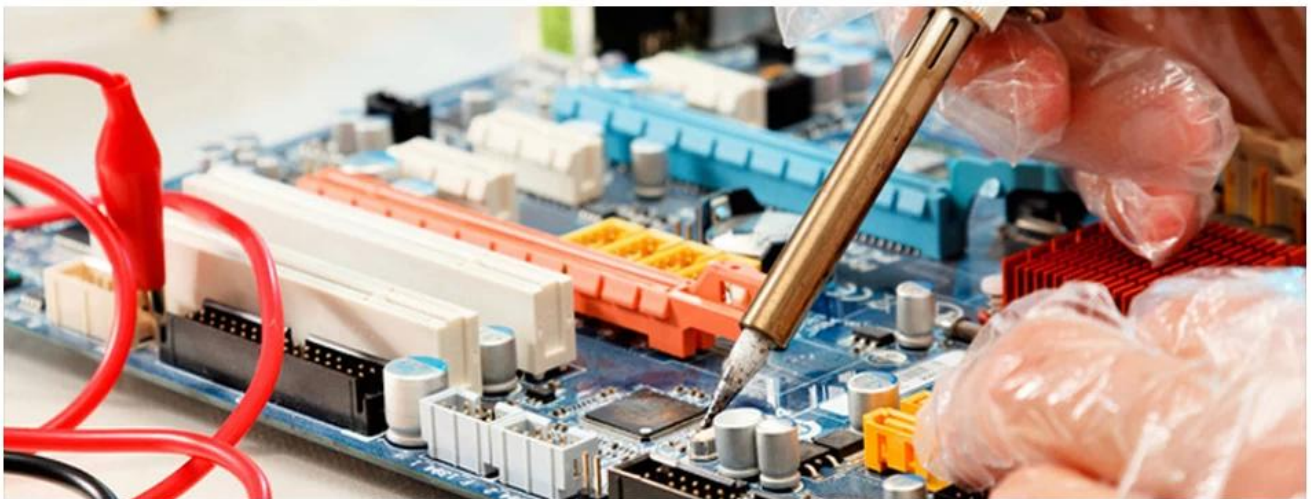
Model: BST-705

Size: $\phi 35 \times 20$ mm

Weight: 40g

Composition: SN99/AG0.3/CU0.7

Melting point: 226°C~229°C





Storage: Chilled in refrigerator, the best refrigeration temperature is 5°C~10°C.

Features: 1. When continuous printing, its viscosity changes less, which can obtain very stable printing.

2. The circuit with the spacing of 0.4-0.6mm and above can complete fine printing.

3. With excellent weld ability, it can show proper viscosity in different parts.

4. It is suitable for the return welding furnace of general atmosphere and nitrogen.

5. Good weldability can be obtained at extremely high peak temperature.

PRODUCT PHOTOGRAPH





